

Electronic Acknowledgement Receipt

EFS ID:	10351645
Application Number:	10577173
International Application Number:	
Confirmation Number:	1239
Title of Invention:	SEMICONDUCTOR DEVICE WITH PLASTIC PACKAGE MOLDING COMPOUND, SEMICONDUCTOR CHIP AND LEADFRAME AND METHOD FOR PRODUCING THE SAME
First Named Inventor/Applicant Name:	Wolfgang Hetzel
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Filer Authorized By:	Mark L. Gleason
Attorney Docket Number:	I441.141.101
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Application Type:	U.S. National Stage under 35 USC 371

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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
1	Issue Fee Payment (PTO-85B)	issuefeepayment.pdf	152201 2beda095ea84ff2738513df2eb064dc39af7b30	no	1

Warnings:**Information:**

2	Miscellaneous Incoming Letter	ChangeofEntityStatus_to_small.pdf	47287 03b273b99d97794ad75bf0c0e31662cb105c88	no	1
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Warnings:**Information:**

3	Fee Worksheet (SB06)	fee-info.pdf	31989 e347bae57340625adfc2c329c2cf68d30a82bfc2	no	2
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Warnings:**Information:**

Total Files Size (in bytes):			231477		
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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.

New International Application Filed with the USPTO as a Receiving Office

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